



SOT684-24(DD)

HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals; 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

31 July 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	10-07-2018
Manufacturer package code	98ASA01261D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	8	-	mm
package width	-	8	-	mm
seated height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



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2 Package outline

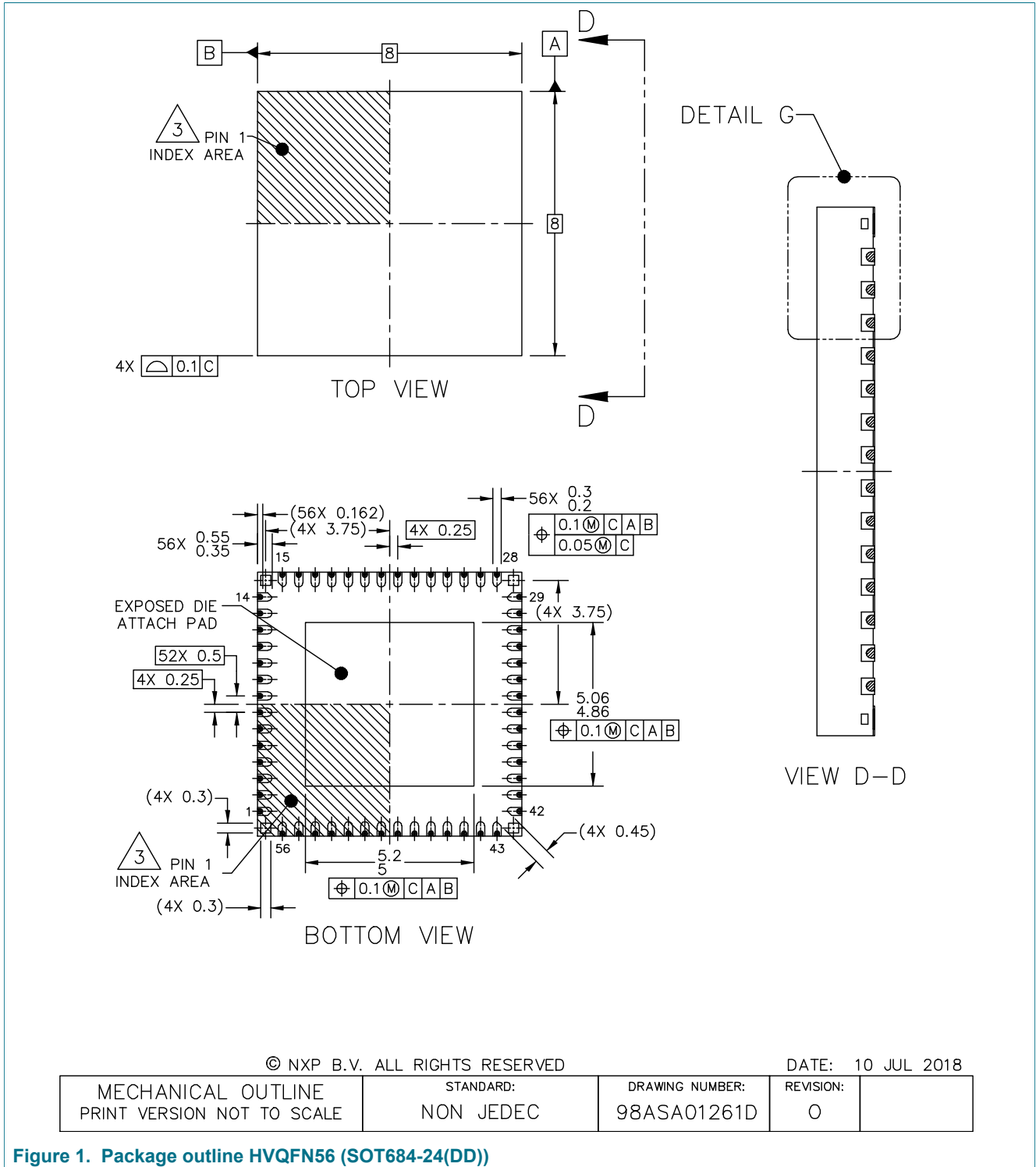
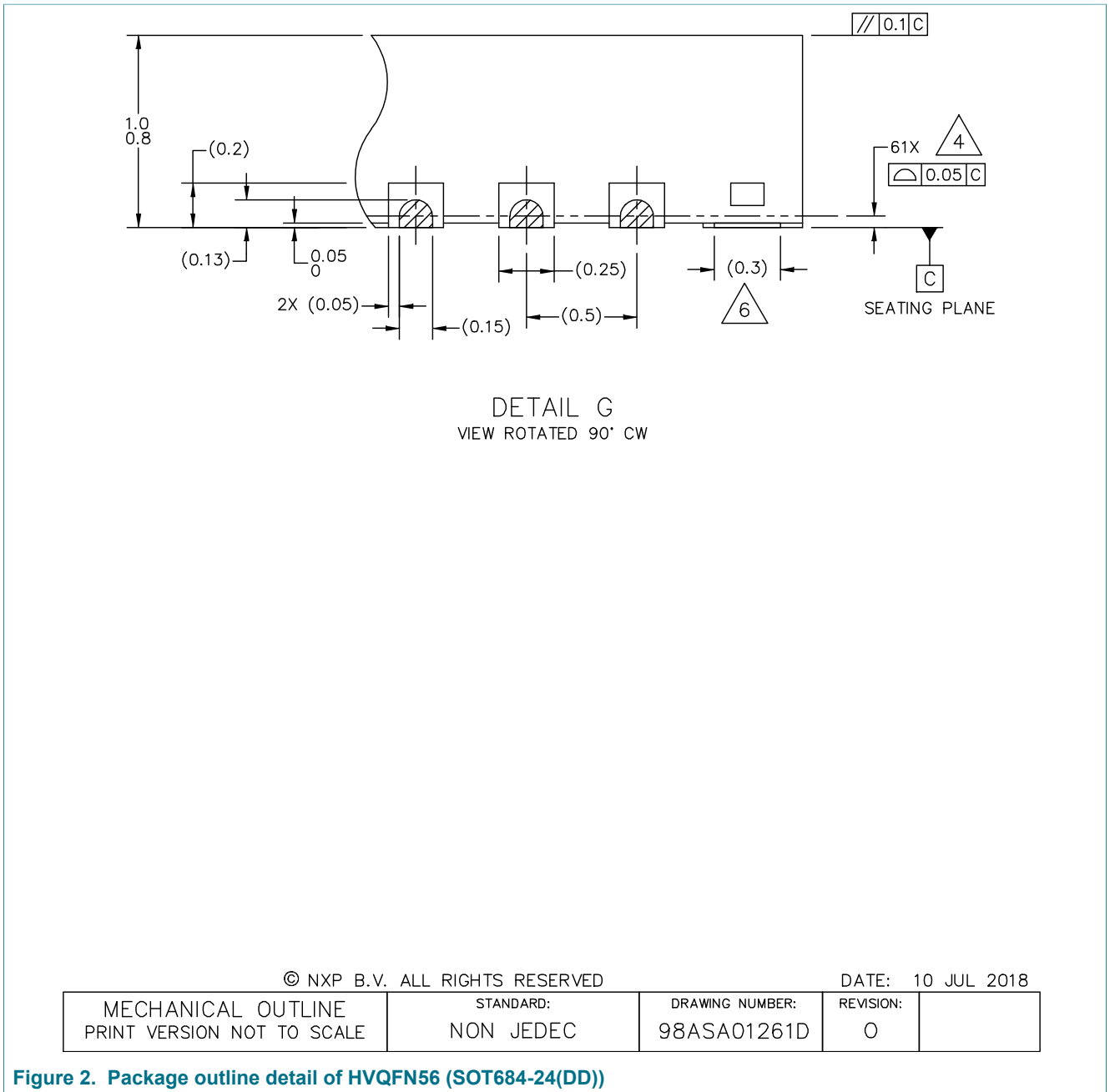


Figure 1. Package outline HVQFN56 (SOT684-24(DD))

HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals;
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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.25 MM.
6. ANCHORING PADS.

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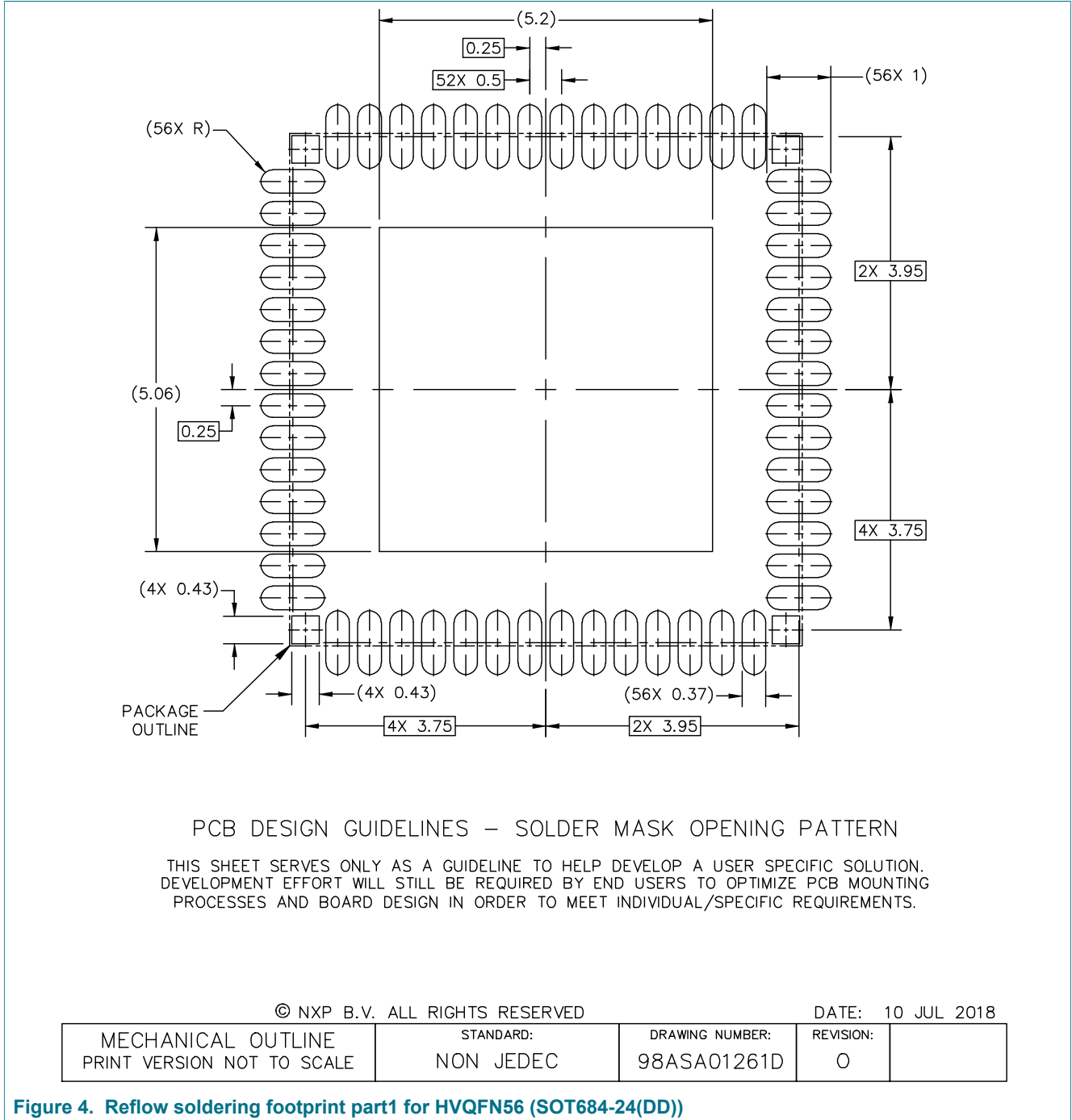
DATE: 10 JUL 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01261D	REVISION: 0	
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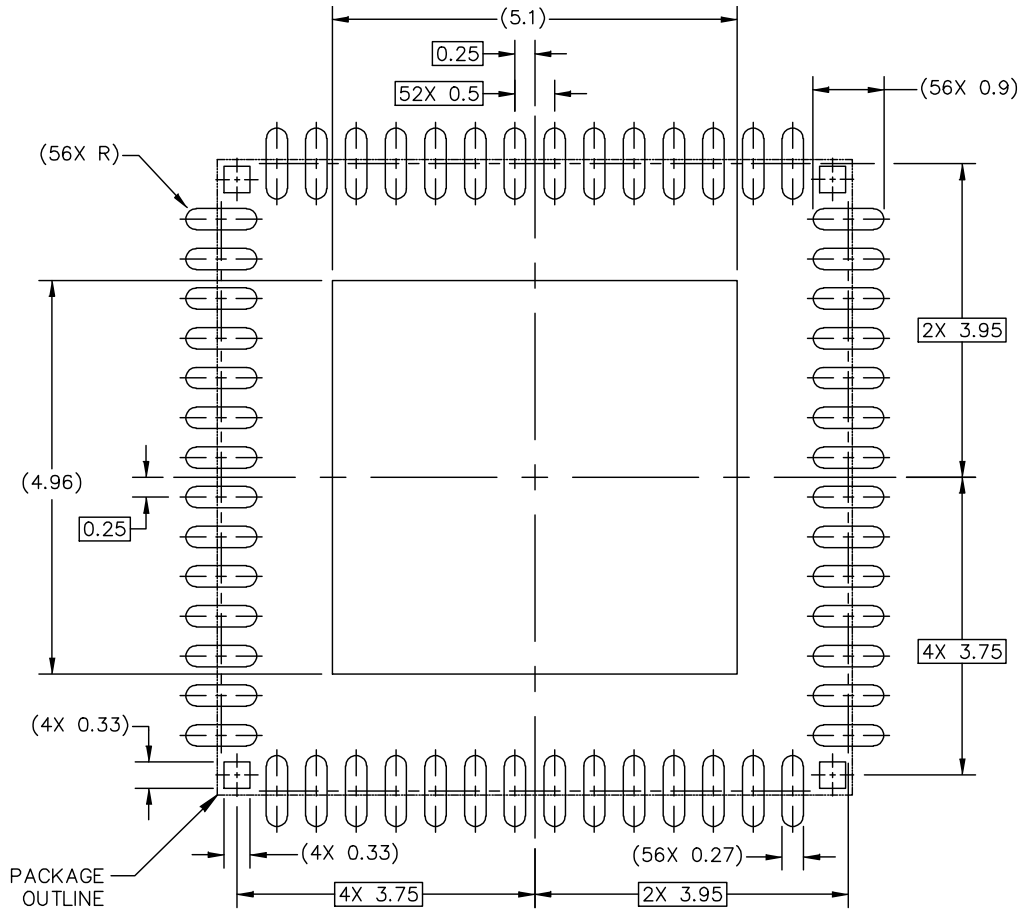
Figure 3. Package outline note HVQFN56 (SOT684-24(DD))

HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals; 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

3 Soldering



HVQFN56, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 56 terminals; 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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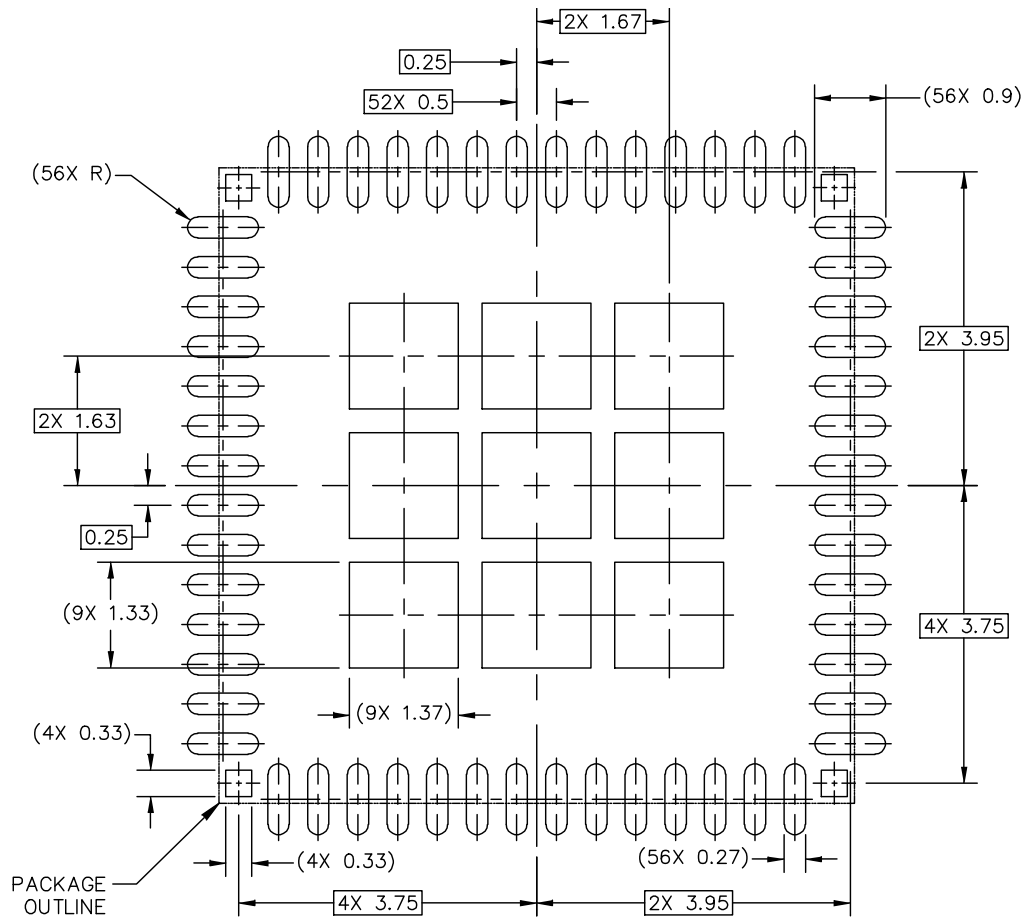
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Figure 5. Reflow soldering footprint part2 for HVQFN56 (SOT684-24(DD))

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 6. Reflow soldering footprint part3 for HVQFN56 (SOT684-24(DD))

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4 Legal information

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